




AP 2813

AMENDMENT TRANSMITTAL LETTER (Large Entity)				Docket No. D730	
Applicant(s): Shields & Ko					
Serial No. 2081325 09/200,326	Filing Date 12/9/98	Examiner T. Nguyen	Group Art Unit 2813		
Invention: EAS CRITICAL TIN ARC LAYER FOR INCREASED PAD ETCH THROUGHPUT				RECEIVED NOV 30 2000 TC 2800 MAIL ROOM	
					
<p align="center"><u>TO THE ASSISTANT COMMISSIONER FOR PATENTS:</u></p> <p>Transmitted herewith is an amendment in the above-identified application. The fee has been calculated and is transmitted as shown below.</p>					
CLAIMS AS AMENDED					
	CLAIMS REMAINING AFTER AMENDMENT	HIGHEST # PREV. PAID FOR	NUMBER EXTRA CLAIMS PRESENT	RATE	ADDITIONAL FEE
TOTAL CLAIMS	4 -	20 =	0 x	\$18.00	\$0.00
INDEP. CLAIMS	1 -	3 =	0 x	\$80.00	\$0.00
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>					\$0.00
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT					\$0.00
<div><div><input checked="" type="checkbox"/> No additional fee is required for amendment. <input type="checkbox"/> Please charge Deposit Account No. _____ in the amount of _____ A duplicate copy of this sheet is enclosed. <input type="checkbox"/> A check in the amount of _____ to cover the filing fee is enclosed. <input checked="" type="checkbox"/> The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. 01-0365 A duplicate copy of this sheet is enclosed. <input checked="" type="checkbox"/> Any additional filing fees required under 37 C.F.R. 1.16. <input checked="" type="checkbox"/> Any patent application processing fees under 37 CFR 1.17.</div><div>RECEIVED NOV 29 2000 TC 2800 MAIL ROOM</div></div>					
 Signature			Dated: 11/17/00		
H. Donald Nelson, Reg. No. 28,980					
<div>RECEIVED NOV 29 2000 TC 2800 MAIL ROOM</div>			I certify that this document and fee is being deposited on 11/17/00 with the U.S. Postal Service as first class mail under 37 C.F.R. 1.8 and is addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.		
			 Signature of Person Mailing Correspondence		
			H. Donald Nelson Typed or Printed Name of Person Mailing Correspondence		

cc:



PATENT

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12/1/00IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Shields & Ko

Assignee: Advanced Micro Devices, Inc.

Title: A SACRIFICIAL TiN ARC LAYER FOR INCREASED PAD ETCH THROUGHPUT

Serial No.: 09/208,325

Filed: 12/9/98

Examiner: T. Nguyen

Group Art Unit: 2813

Attorney Docket No.: D730

Anthem, Arizona
November 17, 2000COMMISSIONER OF PATENTS AND TRADEMARKS
Washington, D.C. 20231AMENDMENT AFTER FINAL ✓

Sir:

In response to the Examiner's Final Office Action of 9/14/00, please amend the above cited application as follows.

In the Claims

Please amend the claims as follows. In accordance with the new rules, if a claim is amended, a marked up version of the claim is included along with a clean version and, in addition, a clean set of all the claims is included.

Please amend Claims 1 & 5 as follows:

1. (Twice amended) A method of manufacturing a semiconductor device, wherein the method comprises:

forming a final layer of metal on a layer of interlayer dielectric in the semiconductor device;
forming a layer of TiN on the final layer of metal;
forming a first layer of photoresist on the layer of TiN;
patterning and developing the first layer of photoresist exposing portions of the layer of TiN;
etching holes in the layer of TiN and the final layer of metal exposing portions of the

interlayer dielectric, wherein metal structures are formed;

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